ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-	C. Bannockb	ourn. Illinois. A	ll rights reserved un ntions.	der both	This docume level parts, t	ent is a declaratio the declaration en	n of the substan compasses all lo	ces within the manufactur wer level materials for w	rer listed ite which the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informati				on				
Supplier Information													
Company name* Company			v unique ID			Unique ID Authority				Response Date*			
onsemi										2025-06-03			
Contact Name Title - Contact			et	P			Phone - Contact*			Email - Contact*			
Product-Env-Stewards Product Envi			viro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			sentative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product			duct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	Manufacturing Site	v	Veight*	UOM	Unit Type	
	FFSD060	FSD0665A 650V 6A SIC SB)		2025-06-03 CPA		СРА	3	29.241	mg	Each	
Manufacturing Proccess Informat	ion												
Terminal Plating / Grid Array Mat	Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy J-	STD-020 MSL	Rating	Peak Proces	s Body Temper	ature Max Time at Peak	Temperatu	ire Numbe	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	second	ls 3				
Comments													
evel 1 - maximum time at peak temperatu	re during sol	ldering is 10-3	0 seconds										
for more information regarding material o	omposition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	5.16	mg	Supplier	Silicon Carbide	409-21-2		5.16	mg	
Die Attach Solder	5.026	mg	Supplier	Silver (Ag)	7440-22-4		0.1257	mg	
			А	Lead (Pb)	7439-92-1	7a	4.6491	mg	
			Supplier	Tin (Sn)	7440-31-5		0.2513	mg	
Lead Frame	167.854	mg	Supplier	Tin (Sn)	7440-31-5		0.168	mg	
			В	Nickel (Ni)	7440-02-0		0.168	mg	
			Supplier	Copper (Cu)	7440-50-8		167.518	mg	
Mold Compound-Black	149.268	mg		Epoxy resin	proprietary data		8.9561	mg	
			Supplier	Phenolic Resin	Proprietary Data		8.9561	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.7463	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		126.8778	mg	
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.7317	mg	
Plating	1.092	mg	Supplier	Tin (Sn)	7440-31-5		1.092	mg	
Wire Bond - Al	0.841	mg	Supplier	Aluminum (Al)	7429-90-5		0.841	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signar range of distribution unless otherwise noted)